

Title (en)
ORGANIC COMPOSITIONS

Title (de)
ORGANISCHE ZUSAMMENSETZUNGEN

Title (fr)
COMPOSITIONS ORGANIQUES

Publication
EP 1461370 A1 20040929 (EN)

Application
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Priority
US 0150182 W 20011231

Abstract (en)
[origin: WO03057749A1] The present composition provides a composition comprising: (a) thermosetting component wherein the thermosetting component comprises monomer having the structure $\text{R}_1\text{R}_2\text{R}_3\text{R}_4\text{R}_5\text{R}_6$ or a mixture of the monomer and the dimer wherein Y is selected from cage compound and silicon atom; R1, R2, R3, R4, R5, and R6 are independently selected from aryl, branched aryl, and arylene ether; at least one of the aryl, the branched aryl, and the arylene ether has an ethynyl group; R7 is aryl or substituted aryl; and at least one of the R1, R2, R3, R4, R5, and R6 comprises at least two isomers; and (b) adhesion promoter comprising compound having at least bifunctionality wherein the bifunctionality may be the same or different and the first functionality is capable of interacting with the thermosetting component (a) and the second functionality is capable of interacting with a substrate when the composition is applied to a substrate. The present composition is particularly useful as a dielectric material in microelectronic applications.

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IPC 8 full level
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